



Semiconductor Device Type: (NYA) 024 VQFN 4x4x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4			
Basic Substance	CAS Number	Contained In Sub-Component	% Total Weight	mg/part	ppm	22.72	(mg) Total	Mold Compound	% of Total Weight	53.84		
Fused Silica	60676-86-0	Mold Compound	48.187	20.335	481,868			Fused Silica	60676-86-0	89.50		
Epoxy Resin	Trade Secret	Mold Compound	2.692	1.136	26,920			Epoxy Resin	Trade Secret	5.00		
Phenol Resin	Trade Secret	Mold Compound	2.154	0.909	21,536			Phenol Resin	Trade Secret	4.00		
Aromatic Phosphate	Trade Secret	Mold Compound	0.700	0.295	6,999			Aromatic Phosphate	Trade Secret	1.30		
Carbon Black	1333-86-4	Mold Compound	0.108	0.045	1,077			Carbon Black	1333-86-4	0.20		
Copper	7440-50-8	Lead Frame	40.302	17.007	403,017			Total		100.00		
Iron	7439-89-6	Lead Frame	0.953	0.402	9,527	17.48	(mg) Total	Lead Frame		% of Total Weight	41.42	
Phosphorous	7723-14-0	Lead Frame	0.104	0.044	1,036			Copper	7440-50-8	97.30		
Zinc (Metal)	7440-66-6	Lead Frame	0.062	0.026	621			Iron	7439-89-6	2.30		
Silver	7440-22-4	Die Attach	0.100	0.042	1,001			Phosphorous	7723-14-0	0.25		
Acrylic Resin	Trade secret	Die Attach	0.018	0.008	182			Zinc (Metal)	7440-66-6	0.15		
Epoxy Resin	Trade secret	Die Attach	0.012	0.005	117			Total		100.00		
Silicon	7440-21-3	Chip (Die)	1.660	0.701	16,600	0.05	(mg) Total	Die Attach		% of Total Weight	0.13	
Gold	7440-57-5	Wire Bond	0.520	0.219	5,200			Silver	7440-22-4	77.00		
Nickel	7440-02-0	Plating on external leads (pins)	2.368	0.999	23,678			Acrylic Resin	Trade secret	14.00		
Palladium	7440-05-3	Plating on external leads (pins)	0.050	0.021	501			Epoxy Resin	Trade secret	9.00		
Gold	7440-57-5	Plating on external leads (pins)	0.012	0.005	122			Total		100.00		
0.0422 g Total Mass			TOTALS:	100.000	42.200	1,000,000	0.70	Total (mg)	Chip (Die)	% of Total Weight	1.66	
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)								Doped Silicon	7440-21-3	100.00		
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.								Total		100.00		
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.								0.22	(mg) Total	Wire Bond	% of Total Weight	0.52
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/									Gold	7440-57-5	100.00	
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.								Total		100.00		
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in microchip technology incorporated in semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.								1.03	(mg) Total	Plating on external leads (pins)	% of Total Weight	2.43
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Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.									Palladium	7440-05-3	2.06	
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table									Gold	7440-57-5	0.50	
								Total		100.00		

42.20

100.00